

## RESPONSE TO OFFICE ACTION

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**IN THE CLAIMS**

1. (Currently Amended) A method of reducing notching in etched anisotropic openings in silicon over an insulator layer comprising:

anisotropically etching openings in silicon with a sulfur hexafluoride etchant in a plasma etch chamber fitted with a powered substrate support while applying pulsed bias power to the a substrate support electrode during the etch step; and

overetching the silicon while applying pulsed bias power to the substrate support electrode.

2. (Currently Amended) A method according to claim 1, wherein the applied bias power to the substrate support electrode during the etching step is from 3 to 100 Watts.

3. (Cancelled)

3 4. (Currently Amended) A method according to claim 2, wherein ~~the~~ pulsed bias power during the etching step is applied at a duty cycle of 10% to 80% using a 6 microsecond period.

4 5. (Currently Amended) A method according to claim <sup>3</sup>~~4~~, wherein the pulsed bias power during the etching step is applied at a duty cycle of 35%.

5 6. (Original) A method according to claim 1 wherein, prior to etching, a deposition step using a fluorocarbon or hydrofluorocarbon gas is used to deposit a fluorine-containing polymer over the substrate.

7. (Cancelled)

6 8. (Original) A method according to claim <sup>5</sup>~~6~~ wherein no bias power is used during the deposition step.

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8. (Original) A method according to claim <sup>S</sup>8 wherein the pressure in the chamber is maintained at about 5 to 300 millitorr during the deposition step.

10. (Cancelled)

11. (Previously presented) A method according to claim <sup>S</sup>8 wherein etching is carried out in the absence of oxygen.

12-13. (Cancelled)

9. 14. (Previously Presented) A method according to claim 1 wherein, prior to overetching, a deposition step using a fluorocarbon or hydrofluorocarbon gas is used to deposit a fluorine-containing polymer over the substrate.

10. 15. (New) A method according to claim 1, wherein the applied bias power to the substrate support electrode during the overetching step is from 3 to 100 Watts.

11. 16. (New) A method according to claim <sup>I</sup>15, wherein the pulsed bias power during the overetching step is applied at a duty cycle in the range of 10% to 80% using a 6 microsecond period.

12. 17. (New) A method according to claim <sup>II</sup>16, wherein the pulsed bias power during the overetching step is applied at a duty cycle of 35%.